



+ CONNECTORS
DISCRETE SOCKETS



✓ Active

TE CONNECTIVITY (TE)
SOCKET,MIN-SPR W/H SN-AU SER-4
[MINI-SPRING SOCKETS](#) | [Series 5](#)

2-5332070-5
TE Internal Number: 2-5332070-5

- [EU RoHS Compliant](#)
- [EU ELV Compliant](#)
- Hole Size (Recommended)** 1.83 mm [.072 in]
- Socket Length** 3.63 mm [.143 in]
- Sealant** Without
- Sleeve Style** Open Bottom
- Wire/Cable Size** .41 – .518 mm² [20 – 21 AWG]

↓ **PRODUCT DRAWING**
[English](#)

↓ **3D PDF**

DOCUMENTATION

Product Drawings

MINIATURE SPRING SOCKET ASSEMBLY SERIES 4
PDF
English

CAD Files

Customer View Model
2D_DXF.ZIP
English

3D PDF
PDF
3D

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

- Sleeve Style Open Bottom
- Connector System Cable-to-Board
- Sealable No
- Connector & Contact Terminates To Printed Circuit Board
- Product Type Contact
- Profile Zero
- Wire/Cable Type Discrete Wire

Body Features

- Sealant Without
- Sleeve Plating Material Tin
- Sleeve Material Copper

Contact Features

- Contact Current Rating (Max) (A) 6.5
- Contact Type Socket
- Contact Spring Plating Thickness .685 μm [30 μin]
- Contact Spring Plating Material Gold
- Contact Mating Area Plating Thickness 30 μm [30 μin]
- Contact Transmits (Typical) Signal (Data)/Power
- Contact Base Material Beryllium Copper
- Socket Type Discrete

Termination Features

- Termination Method to PC Board Through Hole - Press-Fit
- Termination Method to Wire/Cable Solder
- Insertion Method Hand/Semi-Automatic

Dimensions

- Socket Length 3.63 mm [.143 in]
- Hole Size (Recommended) 1.83 mm [.072 in]
- Wire/Cable Size .41 – .518 mm² [20 – 21 AWG]
- Mating Pin Diameter Range .76 – .84 mm [.03 – .033 in]
- PCB Thickness (Recommended) .79 – 3.18 mm [.031 – .125 in]

Usage Conditions

Operating Temperature Range -65 – 125 °C [-85 – 257 °F]

Operation/Application

Circuit Application Power, Signal

Packaging Features

Packaging Method Bag, Loose Piece

Packaging Quantity 2000

Other

Spring Material Beryllium Copper

PRODUCT COMPLIANCE



Statement of Compliance

Statement of Compliance

PDF